

Selection Guide

Part No.	Emitting Color (Material)	Lens Type	Po (mW/sr) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KP-2012SF4C	Infrared (GaAlAs)	Water Clear	0.8	1.5	160°

Notes:

1. $\theta_{1/2}$ is the angle from optical centerline where the luminous intensity is 1 / 2 of the optical peak value.
2. Radiant intensity / luminous Flux: + / -15%.
3. Radiant intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

Parameter	P/N	Symbol	Typ.	Max.	Units	Test Conditions
Forward Voltage [1]	SF4	V _F	1.3	1.6	V	I _F =20mA
Reverse Current	SF4	I _R		10	uA	V _R = 5V
Capacitance	SF4	C	90		pF	V _F =0V;f=1MHz
Peak Spectral Wavelength	SF4	λ _P	880		nm	I _F =20mA
Spectral Bandwidth	SF4	Δλ1/2	50		nm	I _F =20mA

Notes:

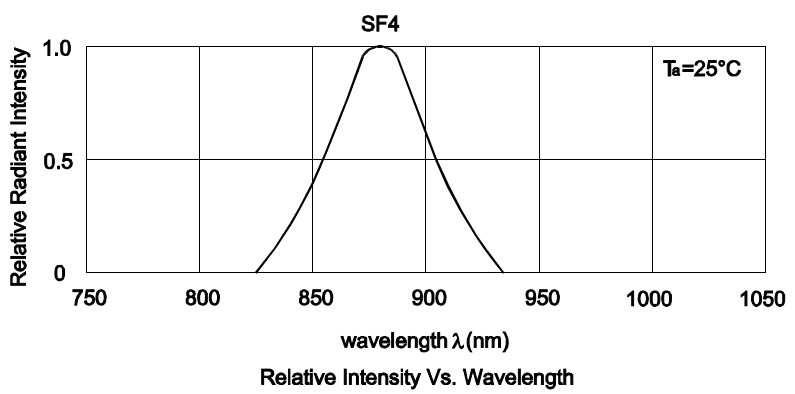
1. Forward Voltage: + / -0.1V.
2. Wavelength value is traceable to CIE127-2007 standards.
3. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

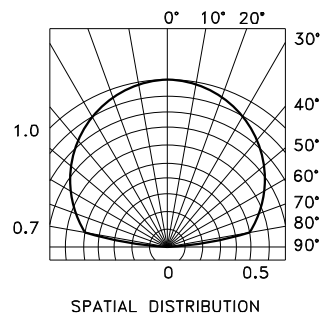
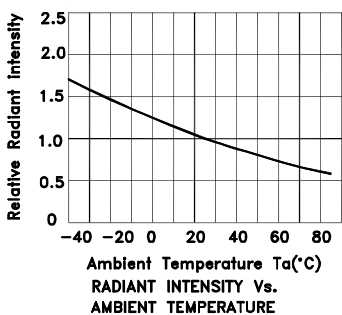
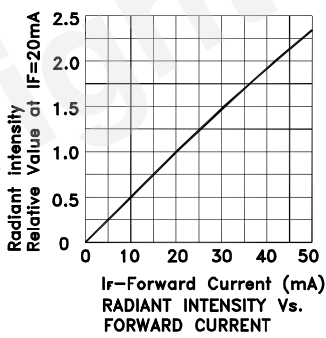
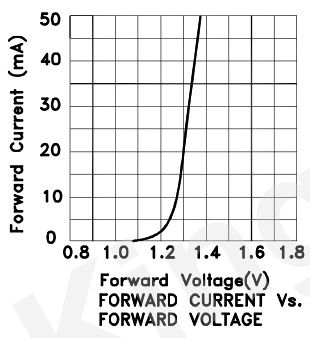
Parameter	Symbol	Values	Units
Power dissipation	P _D	80	mW
DC Forward Current	I _F	50	mA
Peak Forward Current [1]	i _{FS}	1.2	A
Reverse Voltage	V _R	5	V
Operating Temperature	T _A	-40 To +85	°C
Storage Temperature	T _{STG}	-40 To +85	°C

Notes:

1. 1/100 Duty Cycle, 0.1ms Pulse Width.
2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



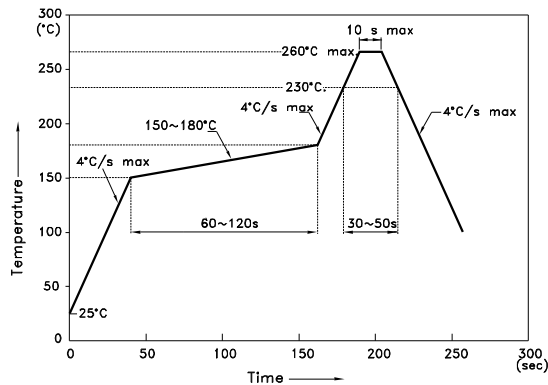
KP-2012SF4C



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Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

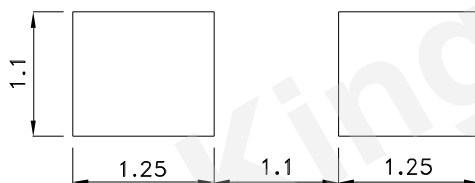
Reflow Soldering Profile For Lead-free SMT Process.



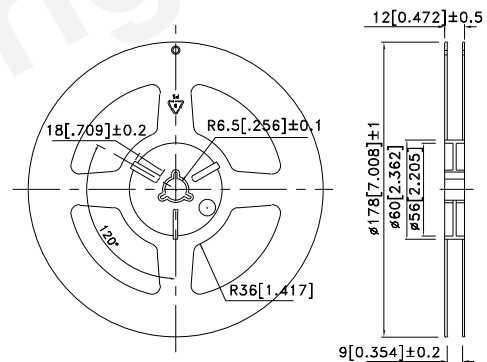
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

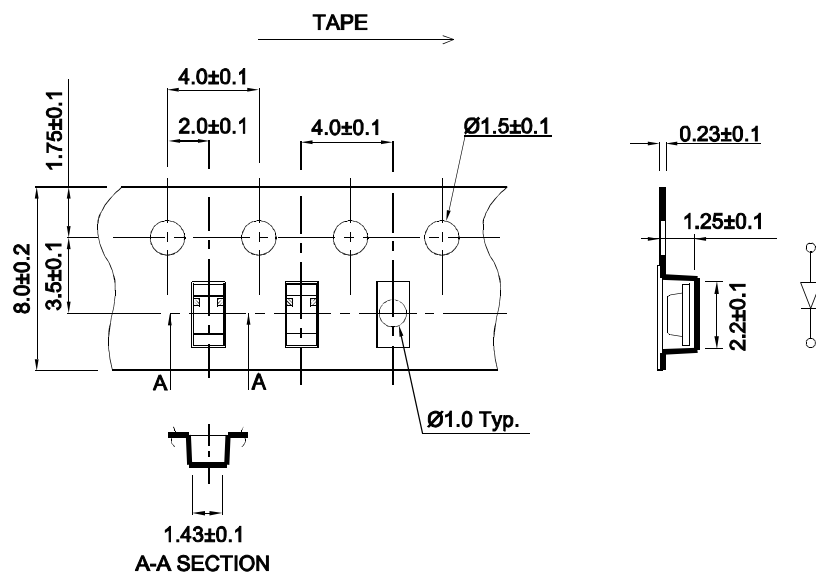
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension

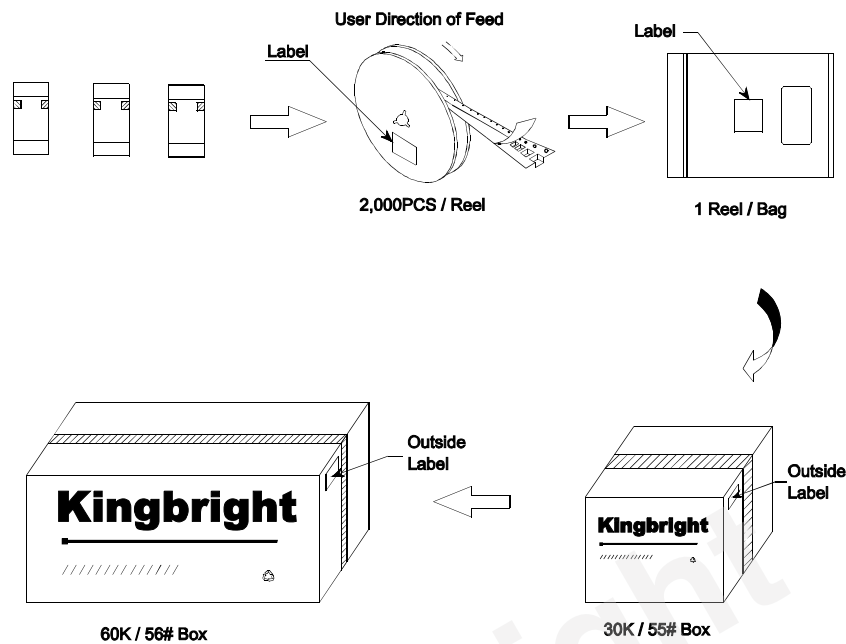


Tape Specifications (Units : mm)



PACKING & LABEL SPECIFICATIONS

KP-2012SF4C



Kingbright	
P/NO: KP-2012xxx	
QTY: 2,000 PCS	Q.C.
S/N: XXXX	Q C XX XX XXXX PASSED
CODE: XXX	
LOT NO:	
RoHS Compliant	

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